

### Technical Data Sheet Top Infrared LED IR67-21C/L261/S65/TR8

#### Features

- Compatible with infrared and vapor phase reflow solder process.
- Low forward voltage.
- View angle 120°
- Pb free
- The product itself will remain within RoHS compliant version.



#### Description

- IR67-21C/L261/S65/TR8 is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with flat top view lens.
- The device is spectrally matched with silicon photodiode and phototransistor.

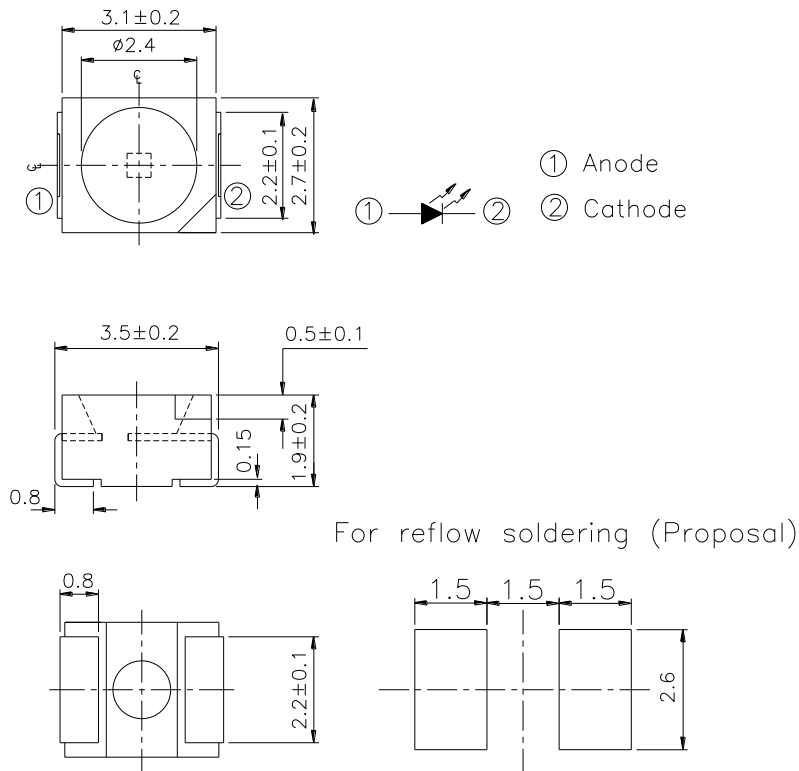
#### Applications

- Sensor
- Optoelectronic switch
- Camera
- VCR
- Video
- Smoke detector

#### Device Selection Guide

Device No.	Chip Material	Lens Color
IR67-21C/L261/S65/TR8	GaAlAs	Water Clear

**Package Dimensions**



- Notes:** 1.All dimensions are in millimeters  
2.Tolerances unless dimensions  $\pm 0.1\text{mm}$

**Absolute Maximum Ratings ( $T_a=25^\circ\text{C}$ )**

Parameter	Symbol	Rating	Unit
Continuous Forward Current	$I_F$	65	mA
Peak Forward Current *1	$I_{FP}$	1	A
Surge Forward Current *2	$I_{FS}$	2	A
Reverse Voltage	$V_R$	5	V
Operating Temperature	$T_{opr}$	-40~ +85	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-40 ~ +100	$^\circ\text{C}$
Soldering Temperature *3	$T_{sol}$	260	$^\circ\text{C}$
Power Dissipation at(or below) 25 $^\circ\text{C}$ Free Air Temperature	$P_d$	130	mW
Temperature resistance junction ambient	$R_{thj-a}$	400	$^\circ\text{C}/\text{W}$

- Notes:** \*1: $I_{FP}$  Conditions--Pulse Width  $\leq 100\mu\text{ s}$  and Duty  $\leq 1\%$ .  
\*2: $I_{FS}$  Conditions--Pulse Width  $\leq 100\mu\text{ s}$   
\*3:Soldering time  $\leq 5$  seconds.

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Radiant Intensity	I <sub>E</sub>	I <sub>F</sub> =20mA	1.0	2.0	3.5	mW /sr
		I <sub>F</sub> =100mA Pulse Width ≤ 100μ s ,Duty ≤ 1%	4.0	8.0	--	
Total Radiated Power	P <sub>o</sub>	I <sub>F</sub> =100mA	--	20	--	mW
Peak Wavelength	λ <sub>p</sub>	I <sub>F</sub> =20mA	--	940	--	nm
Spectral Bandwidth	Δ λ	I <sub>F</sub> =20mA	--	50	--	nm
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =20mA	--	1.20	1.60	V
		I <sub>F</sub> =100mA Pulse Width ≤ 100μ s ,Duty ≤ 1%	--	1.45	1.80	
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	--	--	10	μ A
View Angle	2θ 1/2	I <sub>F</sub> =20mA	--	120	--	deg
Active chip area	A	----	0.122			mm <sup>2</sup>
Dimensions of the active chip area	L×W	----	0.350*0.350			mm×mm

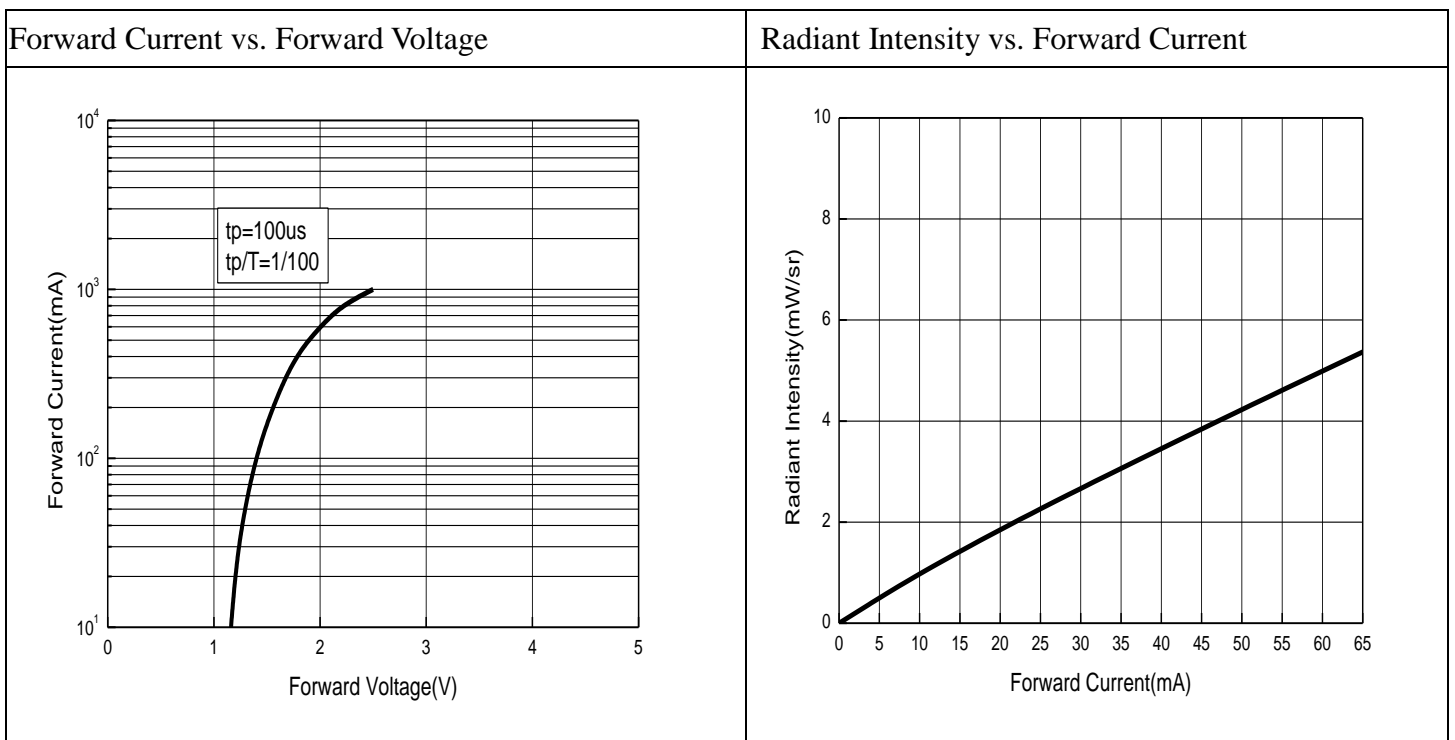
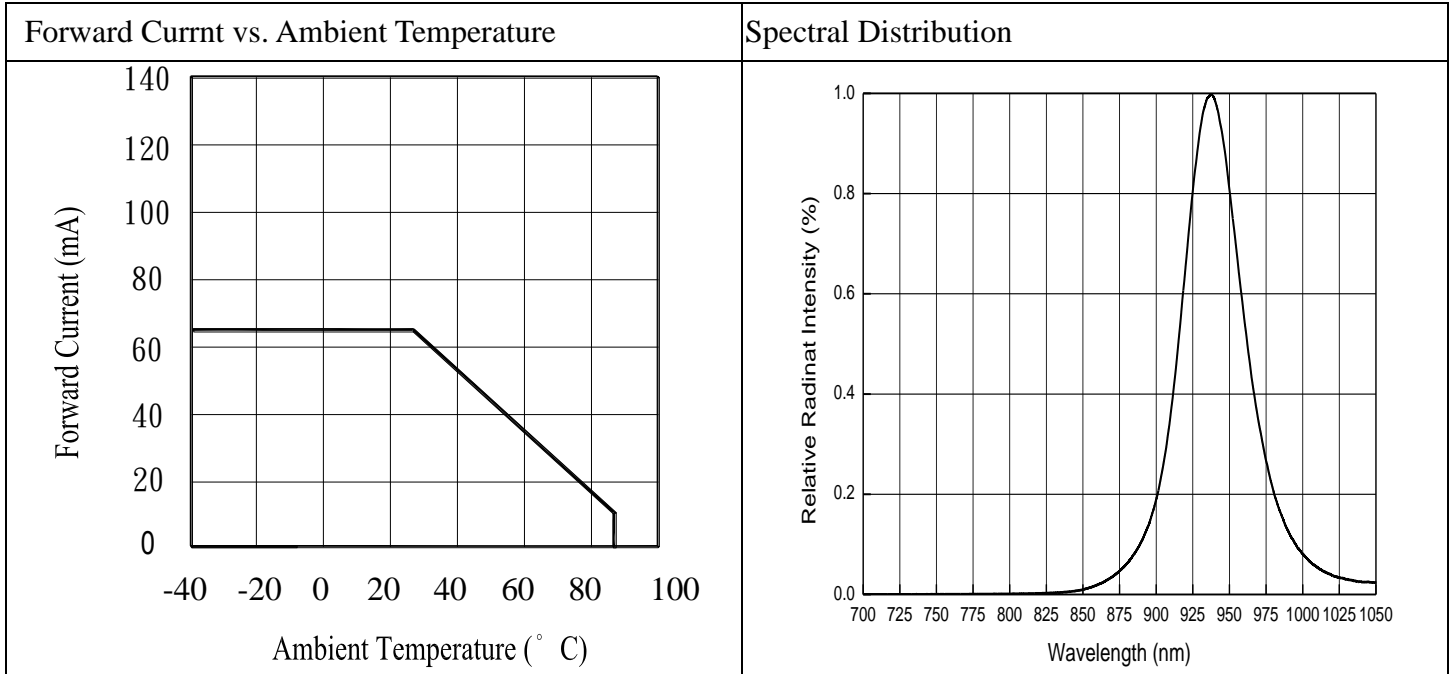
**Rank**

Condition : I<sub>F</sub>=20mA

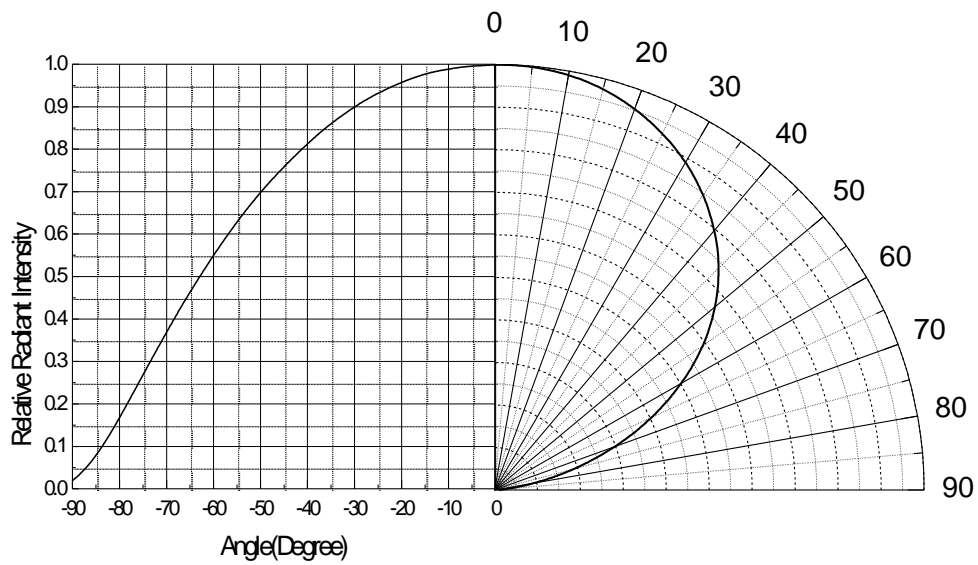
Unit : mW/sr

Bin Number	G	H
Min	1.0	2.0
Max	2.5	3.5

Typical Electrical/Optical/Characteristics Curves for IR



Relative Radiant Intensity vs. Angular Displacement



● **Precautions For Use**

1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change ( Burn out will happen ).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.

2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30°C or less and 70%RH or less.

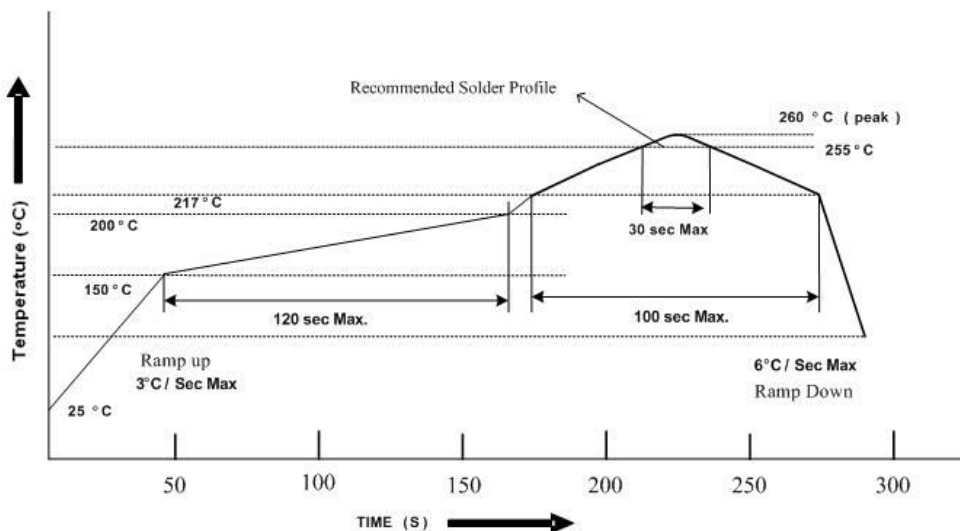
2.5 The LEDs should be used within 168 hours (7 days) after opening the package.

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.

#### 4. Soldering Iron

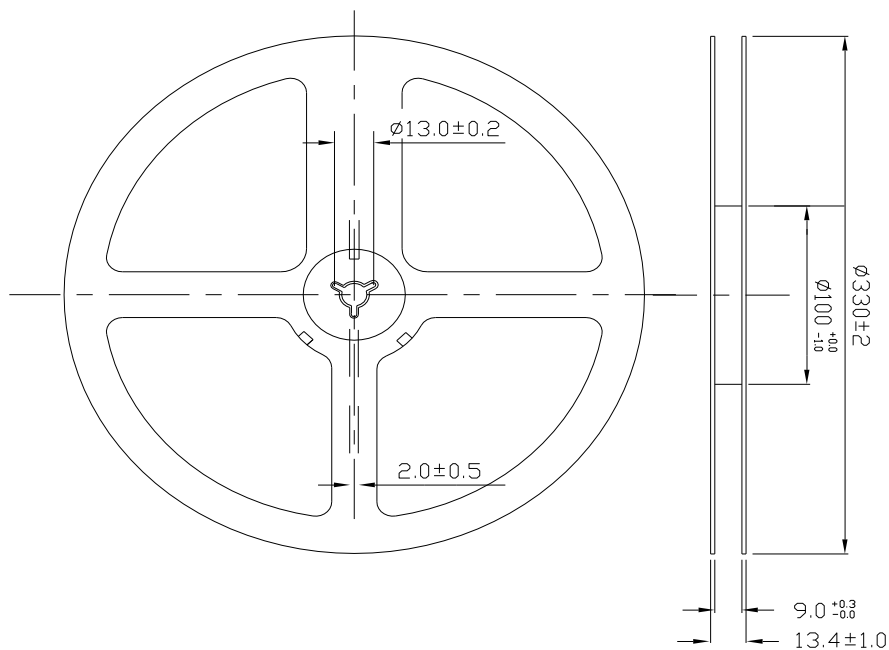
Each terminal is to go to the tip of soldering iron temperature less than  $350^{\circ}\text{C}$  for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

#### 5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

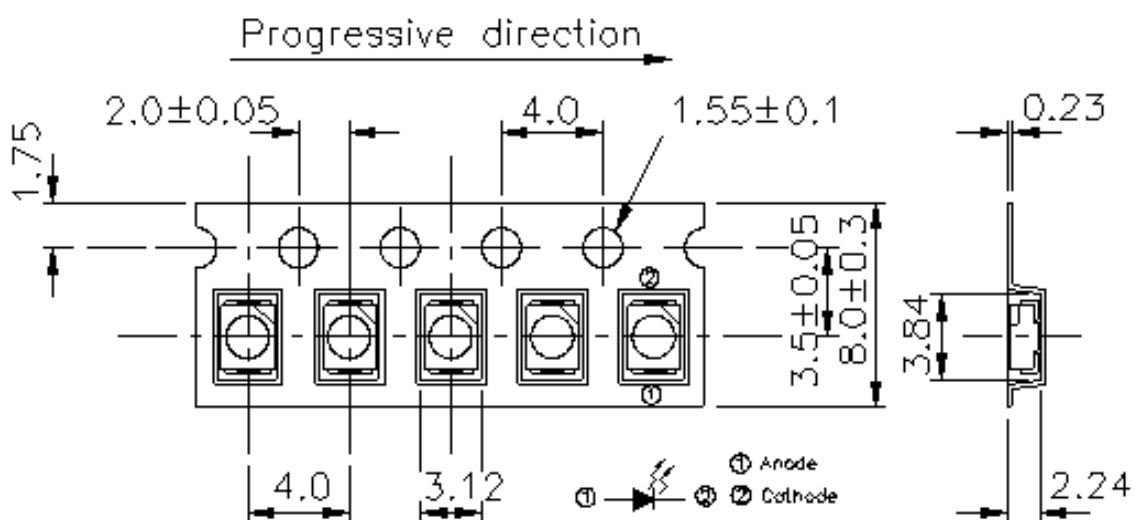


### Package Dimensions



**Note:** The tolerances unless mentioned is  $\pm 0.1$ mm ,Unit = mm

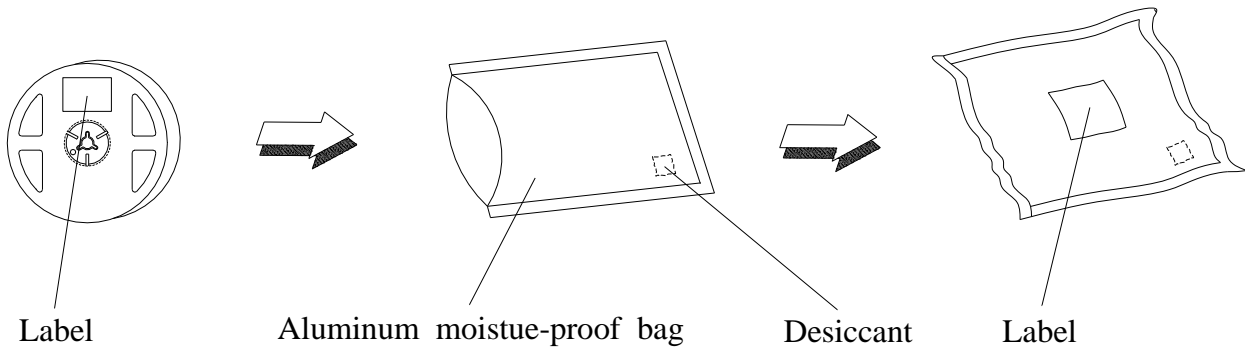
### 2. Carrier Tape Dimensions:(Quantity: 8000pcs/reel)



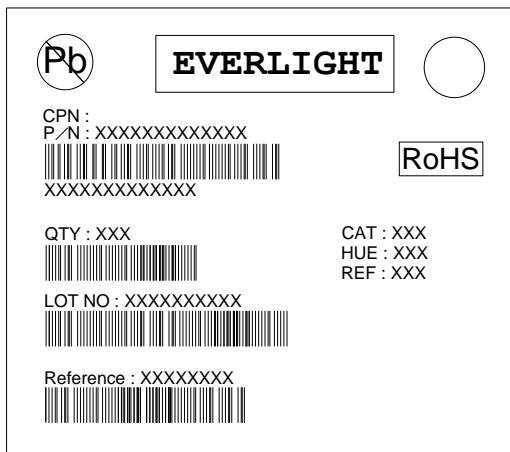
**Note:** The tolerances unless dimension is  $\pm 0.1$ mm ,Unit = mm



## Packing Procedure



## Label Form Specification



CPN: Customer's Production Number  
P/N : Production Number  
QTY: Packing Quantity  
CAT: Ranks  
HUE: Peak Wavelength  
REF: Reference  
LOT No: Lot Number  
MADE IN TAIWAN: Production Place

## Notes

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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